

2022 HYPACK® SOFTWARE PRODUCTS



	ECHO	SURVEY	LITE	HYPACK MAX	HYPACK OFFICE	HYSWEEP	HYSWEEP OFFICE	SURVEY & HYSWEEP	MAX & HYSWEEP	OFFICE & HYSWEEP OFFICE	DREDGEPACK	WATER QUALITY MAPPING	GEOPHYSICS
Survey / Dredge Planning	*	*	*	*	*	*	*	*	*	*	*	*	*
Complete Single Beam Data Collection	*	*	*	*				*	*				
Basic Single Beam Data Collection		*	*	*				*	*				*
Single Beam Editing	*		*	*	*			*	*	*		*	
USV / ASV Support	*	*	*	*				*	*			*	*
Data Thinning (Sort) & Contour	*		*	*	*			*	*			*	*
Plotting	*			*	*			*	*			*	*
Cross Sections & Volume Computation				*	*			*	*				
ENC (S-57) Chart Generation				*	*			*	*				
Real Time Dredge Monitoring											*		
Side Scan Data Collection		*	*	*				*	*				*
Side Scan Data Processing			*	*	*			*	*				*
Sub-Bottom Data Collection		*	*	*				*	*				*
Sub-Bottom Processing			*	*	*			*	*				*
Magnetometer Collection		*	*	*				*	*				*
Magnetometer Editing			*	*				*	*				*
Environmental Data Processing		*	*	*				*	*			*	
Acoustic Doppler Current Profiler (ADCP) Support		*	*	*				*	*			*	
Multibeam / LiDAR Data Collection						*		*	*				
Multibeam / LiDAR Editing						*	*	*	*	*			

HYPACK® ECHO: Our basic and affordable single beam software package for bathymetric and hydrographic surveying. ECHO is designed specifically to support smaller hydrographic or bathymetric surveys . Support for RTK GPS is included. The Single Beam Editor software provides DXF Contour generation and data thinning.

HYPACK® SURVEY: Survey is a data collection-only software that has no editing or final product tools. The data collection supports single beam, magnetometer, and sub-bottom sensors.

HYPACK® LITE: The LITE software includes data collection from the SURVEY software with the addition of processing tools for the sensor data. The data can be exported to a CAD-GIS package.

HYPACK® MAX: The single beam, side scan, sub-bottom, ADCP, and magnetometer data collection and processing modules are standard features of HYPACK® MAX. Final products may include contours, plotting sheets, output for CAD, fly-through views, cross sections, and volumes calculations.

HYPACK® OFFICE: The data processing and final products version of HYPACK®. You can process all of the data in your office (except multibeam and LiDAR).

HYSWEEP®: The module for the collection and processing of multibeam, backscatter, LiDAR, and water column data. HYSWEEP® requires a HYPACK® license (above) for data collection. As you move from single beam to multibeam surveying, you can just upgrade the package to multibeam by purchasing a HYSWEEP® license add-on or add a separate HYSWEEP® key.

HYSWEEP® OFFICE: A package containing all necessary programs for the processing of multibeam bathymetry, backscatter, LiDAR, and water column data. Export to Esri Raster Files is included.

HYPACK® SURVEY & HYSWEEP®: The recommended combination when outfitting a multibeam survey vessel or USV. It can log any kind of data, including the MBES/LiDAR. It does include support for MBES/LiDAR data processing.

HYPACK® MAX & HYSWEEP®: The full package. Everything you need to design your survey, collect datasets, process data, and generate final products.

HYPACK® OFFICE & HYSWEEP® OFFICE: This combination is recommended for your office. It enables you to design your project, and process single beam and multibeam bathymetry as well as LiDAR data sets all the way to final products.

DREDGEPACK®: A software for dredging control on cutter suction, hopper, excavator and bucket dredges. Improve efficiency and monitor the digging operations. DREDGEPACK® provides you with the design tools to accurately model almost any dredge plan. This is not a package for hydrographic surveying.

HYPACK® WATER QUALITY MAPPING: Software for environmental data collection and processing. Includes support for ADCP and basic bathymetry.

HYPACK® GEOPHYSICS: Combines all tools required for a marine geophysical surveys in a centralized, easy to use interface. A software for side scan, sub-Bottom and magnetometer operations. It helps in locating targets. Collect and mosaic side scan data in real-time and during post processing with over 30 device interfaces.